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Contents

vii	Authors
xi	Conference Committee

SESSION 1	PULSED LASER COMPONENTS AND PACKAGING
10513 04	Inhibited-coupling HC-PCF based beam-delivery-system for high power green industrial lasers [10513-3]
10513 05	2-µm wavelength-range low-loss inhibited-coupling hollow-core PCF [10513-4]
10513 06	Pushing the boundaries of high power lasers: low loss, large area CVD diamond [10513-5]
SESSION 2	ADVANCED LASER PACKAGING SOLUTIONS
10513 08	Fiber-based laser MOPA transmitter packaging for space environment [10513-7]
10513 09	Intensity noise properties of a compact laser device based on a miniaturized MOPA system for spectroscopic applications [10513-8]
SESSION 3	LASER OPTICS AND OPTICAL ASSEMBLY
10513 OF	Beam shaping optics to enhance performance of interferometry techniques in grating manufacture [10513-14]
10513 0G	Compact DFB laser modules with integrated isolator at 935 nm [10513-15]
SESSION 4	LASER DIODE PACKAGING I
10513 OH	Fully utilizing high power diode lasers by synergizing diode laser light sources and beam shaping micro-optics (Invited Paper) [10513-16]
10513 0	Modular high power diode lasers with flexible 3D multiplexing arrangement optimized for automated manufacturing [10513-17]
10513 OK	Scalable pump beam arrangement for diode pumped alkali lasers [10513-19]
SESSION 5	LASER DIODE PACKAGING II
10513 OM	Novel packaging for CW and QCW diode laser modules for operation with high power and duty cycles [10513-21]

10513 00	High temperature semiconductor diode laser pumps for high energy laser applications [10513-23]
10513 0Q	High power vertical stacked and horizontal arrayed diode laser bar development based on insulation micro-channel cooling (IMCC) and hard solder bonding technology [10513-25]
SESSION 6	HIGH POWER/ENERGY LASER COMPONENTS AND PACKAGING I
10513 0\$	Next-generation fiber lasers enabled by high-performance components (Invited Paper) [10513-27]
10513 OT	A low cost hermetic packaging for high power industry fiber lasers [10513-28]
10513 OU	Measurement and removal of cladding light in high power fiber systems [10513-29]
10513 OV	Uncooled pump combiners for fiber laser and amplifier systems [10513-30]
10513 OW	Photonic limiters with enhanced dynamic range [10513-31]
SESSION 7	HIGH POWER/ENERGY LASER COMPONENTS AND PACKAGING II
10513 0X	ICESat-2 laser Nd:YVO4 amplifier (Invited Paper) [10513-32]
10513 OZ	Two-step recording of visible holographic elements in photo-thermo-refractive glass [10513-34]
10513 11	High power multiple wavelength diode laser stack for DPSSL application without temperature control [10513-47]
10513 12	Continuous and pulsed laser high power beam combiner for additive manufacturing applications [10513-36]
SESSION 8	HIGH POWER/ENERGY LASER COMPONENTS AND PACKAGING III
10513 13	Novel high-density packaging of solid state diode pumped eye-safe laser for LIBS (Invited Paper) [10513-37]
SESSION 9	HIGH POWER/ENERGY LASER COMPONENTS AND PACKAGING IV
10513 18	Lasers with intra-cavity phase elements [10513-42]
105131A	Polarizing Gires-Tournois interferometer as intra-cavity frequency-selective element in high-power lasers [10513-44]
10513 1C	High efficiency pump combiner fabricated by CO ₂ laser splicing system [10513-46]

POSTER SESSION

10513 1E	Integrated IoT technology in industrial lasers for the improved user experience [10513-49]
10513 1F	Predicting fiber refractive index from a measured preform index profile [10513-50]
105131G	New approach for high reliability, low loss splicing between silica and ZBLAN fibers [10513-51]
10513 1H	Mid-infrared performance of single mode chalcogenide fibers [10513-52]
10513 11	Measurement methods to build up the digital optical twin [10513-53]
10513 1 J	Exploring the effect of nested capillaries on core-cladding mode resonances in hollow-core antiresonant fibers [10513-54]
10513 1K	Trapezoidal diffraction grating beam splitters in single crystal diamond [10513-55]
10513 1L	Optimized birefringent filter design for multi-wavelength operation of Yb-ion lasers [10513-56]
10513 1M	The research on the design and performance of 7×1 pump combiners [10513-57]
10513 1N	Fabrication of longitudinally arbitrary shaped fiber tapers [10513-58]
1051310	Spectrally resolved, broadband frequency response characterization of photodetectors using continuous-wave supercontinuum sources [10513-59]
10513 1Q	All fiber cladding mode stripper with uniform heat distribution and high cladding light loss manufactured by CO ₂ laser ablation [10513-61]
10513 1R	Study on the near-field non-linearity (SMILE) of high power diode laser arrays [10513-62]